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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Obsolete
Number of LABs/CLBs	600
Number of Logic Elements/Cells	2700
Total RAM Bits	81920
Number of I/O	196
Number of Gates	128236
Voltage - Supply	1.71V ~ 1.89V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	352-LBGA Exposed Pad, Metal
Supplier Device Package	352-MBGA (35x35)
Purchase URL	https://www.e-xfl.com/product-detail/xilinx/xcv100e-8bg352c

resources. The abundance of routing resources permits the Virtex-E family to accommodate even the largest and most complex designs.

Virtex-E FPGAs are SRAM-based, and are customized by loading configuration data into internal memory cells. Configuration data can be read from an external SPROM (master serial mode), or can be written into the FPGA (SelectMAP™, slave serial, and JTAG modes).

The standard Xilinx Foundation Series™ and Alliance Series™ Development systems deliver complete design support for Virtex-E, covering every aspect from behavioral and schematic entry, through simulation, automatic design translation and implementation, to the creation and downloading of a configuration bit stream.

Higher Performance

Virtex-E devices provide better performance than previous generations of FPGAs. Designs can achieve synchronous system clock rates up to 240 MHz including I/O or 622 Mb/s using Source Synchronous data transmission architectures. Virtex-E I/Os comply fully with 3.3 V PCI specifications, and interfaces can be implemented that operate at 33 MHz or 66 MHz.

While performance is design-dependent, many designs operate internally at speeds in excess of 133 MHz and can achieve over 311 MHz. Table 2 shows performance data for representative circuits, using worst-case timing parameters.

Table 2: **Performance for Common Circuit Functions**

Function	Bits	Virtex-E (-7)
Register-to-Register		
Adder	16 64	4.3 ns 6.3 ns
Pipelined Multiplier	8 x 8 16 x 16	4.4 ns 5.1 ns
Address Decoder	16 64	3.8 ns 5.5 ns
16:1 Multiplexer		4.6 ns
Parity Tree	9 18 36	3.5 ns 4.3 ns 5.9 ns
Chip-to-Chip		
HSTL Class IV		
LVTTL,16mA, fast slew		
LVDS		
LVPECL		

Virtex-E Device/Package Combinations and Maximum I/O

Table 3: **Virtex-E Family Maximum User I/O by Device/Package (Excluding Dedicated Clock Pins)**

	XCV 50E	XCV 100E	XCV 200E	XCV 300E	XCV 400E	XCV 600E	XCV 1000E	XCV 1600E	XCV 2000E	XCV 2600E	XCV 3200E
CS144	94	94	94								
PQ240	158	158	158	158	158						
HQ240						158	158				
BG352		196	260	260							
BG432				316	316	316					
BG560					404	404	404	404	404		
FG256	176	176	176	176							
FG456			284	312							
FG676					404	444					
FG680						512	512	512	512		
FG860							660	660	660		
FG900						512	660	700			
FG1156							660	724	804	804	804

Table 1: **Supported I/O Standards**

I/O Standard	Output V_{CCO}	Input V_{CCO}	Input V_{REF}	Board Termination Voltage (V_{TT})
LVTTL	3.3	3.3	N/A	N/A
LVCMOS2	2.5	2.5	N/A	N/A
LVCMOS18	1.8	1.8	N/A	N/A
SSTL3 I & II	3.3	N/A	1.50	1.50
SSTL2 I & II	2.5	N/A	1.25	1.25
GTL	N/A	N/A	0.80	1.20
GTL+	N/A	N/A	1.0	1.50
HSTL I	1.5	N/A	0.75	0.75
HSTL III & IV	1.5	N/A	0.90	1.50
CTT	3.3	N/A	1.50	1.50
AGP-2X	3.3	N/A	1.32	N/A
PCI33_3	3.3	3.3	N/A	N/A
PCI66_3	3.3	3.3	N/A	N/A
BLVDS & LVDS	2.5	N/A	N/A	N/A
LVPECL	3.3	N/A	N/A	N/A

In addition to the CLK and CE control signals, the three flip-flops share a Set/Reset (SR). For each flip-flop, this signal can be independently configured as a synchronous Set, a synchronous Reset, an asynchronous Preset, or an asynchronous Clear.

The output buffer and all of the IOB control signals have independent polarity controls.

All pads are protected against damage from electrostatic discharge (ESD) and from over-voltage transients. After configuration, clamping diodes are connected to V_{CCO} with the exception of LVCMOS18, LVCMOS25, GTL, GTL+, LVDS, and LVPECL.

Optional pull-up, pull-down and weak-keeper circuits are attached to each pad. Prior to configuration all outputs not involved in configuration are forced into their high-impedance state. The pull-down resistors and the weak-keeper circuits are inactive, but I/Os can optionally be pulled up.

The activation of pull-up resistors prior to configuration is controlled on a global basis by the configuration mode pins. If the pull-up resistors are not activated, all the pins are in a high-impedance state. Consequently, external pull-up or pull-down resistors must be provided on pins required to be at a well-defined logic level prior to configuration.

All Virtex-E IOBs support IEEE 1149.1-compatible Boundary Scan testing.

Input Path

The Virtex-E IOB input path routes the input signal directly to internal logic and/ or through an optional input flip-flop.

An optional delay element at the D-input of this flip-flop eliminates pad-to-pad hold time. The delay is matched to the internal clock-distribution delay of the FPGA, and when used, assures that the pad-to-pad hold time is zero.

Each input buffer can be configured to conform to any of the low-voltage signalling standards supported. In some of these standards the input buffer utilizes a user-supplied threshold voltage, V_{REF}. The need to supply V_{REF} imposes constraints on which standards can be used in close proximity to each other. See **I/O Banking**.

There are optional pull-up and pull-down resistors at each user I/O input for use after configuration. Their value is in the range 50 – 100 kΩ.

Output Path

The output path includes a 3-state output buffer that drives the output signal onto the pad. The output signal can be routed to the buffer directly from the internal logic or through an optional IOB output flip-flop.

The 3-state control of the output can also be routed directly from the internal logic or through a flip-flip that provides synchronous enable and disable.

Each output driver can be individually programmed for a wide range of low-voltage signalling standards. Each output buffer can source up to 24 mA and sink up to 48 mA. Drive strength and slew rate controls minimize bus transients.

In most signalling standards, the output High voltage depends on an externally supplied V_{CCO} voltage. The need to supply V_{CCO} imposes constraints on which standards can be used in close proximity to each other. See **I/O Banking**.

An optional weak-keeper circuit is connected to each output. When selected, the circuit monitors the voltage on the pad and weakly drives the pin High or Low to match the input signal. If the pin is connected to a multiple-source signal, the weak keeper holds the signal in its last state if all drivers are disabled. Maintaining a valid logic level in this way eliminates bus chatter.

Since the weak-keeper circuit uses the IOB input buffer to monitor the input level, an appropriate V_{REF} voltage must be provided if the signalling standard requires one. The provision of this voltage must comply with the I/O banking rules.

I/O Banking

Some of the I/O standards described above require V_{CCO} and/or V_{REF} voltages. These voltages are externally supplied and connected to device pins that serve groups of IOBs, called banks. Consequently, restrictions exist about which I/O standards can be combined within a given bank.

Verilog Initialization Example

```
module MYMEM (CLK, WE, ADDR, DIN, DOUT);
input CLK, WE;
input [8:0] ADDR;
input [7:0] DIN;
output [7:0] DOUT;

wire logic0, logic1;

//synopsys dc_script_begin
//set_attribute ram0 INIT_00
"0123456789ABCDEF0123456789ABCDEF0123456789ABCDEF0123456789ABCDEF" -type string
//set_attribute ram0 INIT_01
"FEDCBA9876543210FEDCBA9876543210FEDCBA9876543210FEDCBA9876543210" -type string
//synopsys dc_script_end

assign logic0 = 1'b0;
assign logic1 = 1'b1;

RAMB4_S8 ram0 (.WE(WE), .EN(logic1), .RST(logic0), .CLK(CLK), .ADDR(ADDR), .DI(DIN),
.DO(DOUT));
//synopsys translate_off
defparam ram0.INIT_00 =
256h'0123456789ABCDEF0123456789ABCDEF0123456789ABCDEF0123456789ABCDEF;
defparam ram0.INIT_01 =
256h'FEDCBA9876543210FEDCBA9876543210FEDCBA9876543210FEDCBA9876543210;
//synopsys translate_on
endmodule
```

Using SelectI/O

The Virtex-E FPGA series includes a highly configurable, high-performance I/O resource, called SelectI/O™ to provide support for a wide variety of I/O standards. The SelectI/O resource is a robust set of features including programmable control of output drive strength, slew rate, and input delay and hold time. Taking advantage of the flexibility and SelectI/O features and the design considerations described in this document can improve and simplify system level design.

Introduction

As FPGAs continue to grow in size and capacity, the larger and more complex systems designed for them demand an increased variety of I/O standards. Furthermore, as system clock speeds continue to increase, the need for high performance I/O becomes more important.

While chip-to-chip delays have an increasingly substantial impact on overall system speed, the task of achieving the desired system performance becomes more difficult with the proliferation of low-voltage I/O standards. SelectI/O, the revolutionary input/output resources of Virtex-E devices, resolve this potential problem by providing a highly configurable, high-performance alternative to the I/O resources of more conventional programmable devices. Virtex-E SelectI/O features combine the flexibility and time-to-market advantages of programmable logic with the high performance previously available only with ASICs and custom ICs.

Each SelectI/O block can support up to 20 I/O standards. Supporting such a variety of I/O standards allows the support of a wide variety of applications, from general purpose standard applications to high-speed low-voltage memory buses.

SelectI/O blocks also provide selectable output drive strengths and programmable slew rates for the LVTTL output buffers, as well as an optional, programmable weak pull-up, weak pull-down, or weak “keeper” circuit ideal for use in external bussing applications.

Each Input/Output Block (IOB) includes three registers, one each for the input, output, and 3-state signals within the IOB. These registers are optionally configurable as either a D-type flip-flop or as a level sensitive latch.

The input buffer has an optional delay element used to guarantee a zero hold time requirement for input signals registered within the IOB.

The Virtex-E SelectI/O features also provide dedicated resources for input reference voltage (V_{REF}) and output source voltage (V_{CCO}), along with a convenient banking system that simplifies board design.

By taking advantage of the built-in features and wide variety of I/O standards supported by the SelectI/O features, system-level design and board design can be greatly simplified and improved.

Date	Version	Revision
9/20/00	1.7	• Min values added to **Virtex-E Electrical Characteristics** tables. • XCV2600E and XCV3200E numbers added to **Virtex-E Electrical Characteristics** tables (Module 3). • Corrected user I/O count for XCV100E device in Table 1 (Module 1). • Changed several pins to “No Connect in the XCV100E“ and removed duplicate V_{CCINT} pins in Table ~ (Module 4). • Changed pin J10 to “No connect in XCV600E” in Table 74 (Module 4). • Changed pin J30 to “VREF option only in the XCV600E” in Table 74 (Module 4). • Corrected pair 18 in Table 75 (Module 4) to be “AO in the XCV1000E, XCV1600E“.
11/20/00	1.8	• Upgraded speed grade -8 numbers in **Virtex-E Electrical Characteristics** tables to Preliminary. • Updated minimums in Table 13 and added notes to Table 14. • Added to note 2 to **Absolute Maximum Ratings**. • Changed speed grade -8 numbers for $T_{SHCKO32}$, T_{REG}, T_{BCCS}, and T_{ICKOF}. • Changed all minimum hold times to –0.4 under **Global Clock Set-Up and Hold for LVTTL Standard, with DLL**. • Revised maximum T_{DLLPW} in -6 speed grade for **DLL Timing Parameters**. • Changed GCLK0 to BA22 for FG860 package in Table 46.
2/12/01	1.9	• Revised footnote for Table 14. • Added numbers to **Virtex-E Electrical Characteristics** tables for XCV1000E and XCV2000E devices. • Updated Table 27 and Table 78 to include values for XCV400E and XCV600E devices. • Revised Table 62 to include pinout information for the XCV400E and XCV600E devices in the BG560 package. • Updated footnotes 1 and 2 for Table 76 to include XCV2600E and XCV3200E devices.
4/02/01	2.0	• Updated numerous values in **Virtex-E Switching Characteristics** tables. • Converted data sheet to modularized format. See the **Virtex-E Data Sheet** section.
4/19/01	2.1	• Modified Figure 30 "DLL Generation of 4x Clock in Virtex-E Devices."
07/23/01	2.2	• Made minor edits to text under **Configuration**. • Added CLB column locations for XCV2600E anbd XCV3200E devices in Table 3.
11/09/01	2.3	• Added warning under **Configuration** section that attempting to load an incorrect bitstream causes configuration to fail and can damage the device.
07/17/02	2.4	• Data sheet designation upgraded from Preliminary to Production.
09/10/02	2.5	• Added clarification to the **Input/Output Block**, **Configuration**, **Boundary Scan Mode**, and **Block SelectRAM** sections. Revised Figure 18, Table 11, and Table 36.
11/19/02	2.6	• Added clarification in the **Boundary Scan** section. • Removed last sentence regarding deactivation of duty-cycle correction in **Duty Cycle Correction Property** section.
06/15/04	2.6.1	• Updated clickable web addresses.
01/12/06	2.7	• Updated the **Slave-Serial Mode** and the **Master-Serial Mode** sections.
01/16/06	2.8	• Made minor updates to Table 8.

Power-On Power Supply Requirements

Xilinx FPGAs require a certain amount of supply current during power-on to insure proper device operation. The actual current consumed depends on the power-on ramp rate of the power supply. This is the time required to reach the nominal power supply voltage of the device[1] from 0V. The fastest ramp rate is 0V to nominal voltage in 2 ms, and the slowest allowed ramp rate is 0V to nominal voltage in 50 ms. For more details on power supply requirements, see XAPP158 on www.xilinx.com.

Product (Commercial Grade)	Description(2)	Current Requirement(3)
XCV50E - XCV600E	Minimum required current supply	500 mA
XCV812E - XCV2000E	Minimum required current supply	1 A
XCV2600E - XCV3200E	Minimum required current supply	1.2 A
Virtex-E Family, Industrial Grade	Minimum required current supply	2 A

Notes:
1. Ramp rate used for this specification is from 0 - 1.8 V DC. Peak current occurs on or near the internal power-on reset threshold and lasts for less than 3 ms.
2. Devices are guaranteed to initialize properly with the minimum current available from the power supply as noted above.
3. Larger currents might result if ramp rates are forced to be faster.

DC Input and Output Levels

Values for V_{IL} and V_{IH} are recommended input voltages. Values for I_{OL} and I_{OH} are guaranteed over the recommended operating conditions at the V_{OL} and V_{OH} test points. Only selected standards are tested. These are chosen to ensure that all standards meet their specifications. The selected standards are tested at minimum V_{CCO} with the respective V_{OL} and V_{OH} voltage levels shown. Other standards are sample tested.

Input/Output Standard	V_{IL}		V_{IH}		V_{OL}	V_{OH}	I_{OL}	I_{OH}
	V, Min	V, Max	V, Min	V, Max	V, Max	V, Min	mA	mA
LVTTL(1)	– 0.5	0.8	2.0	3.6	0.4	2.4	24	– 24
LVCMOS2	– 0.5	0.7	1.7	2.7	0.4	1.9	12	– 12
LVCMOS18	– 0.5	35% V_{CCO}	65% V_{CCO}	1.95	0.4	V_{CCO} – 0.4	8	– 8
PCI, 3.3 V	– 0.5	30% V_{CCO}	50% V_{CCO}	V_{CCO} + 0.5	10% V_{CCO}	90% V_{CCO}	Note 2	Note 2
GTL	– 0.5	V_{REF} – 0.05	V_{REF} + 0.05	3.6	0.4	n/a	40	n/a
GTL+	– 0.5	V_{REF} – 0.1	V_{REF} + 0.1	3.6	0.6	n/a	36	n/a
HSTL I(3)	– 0.5	V_{REF} – 0.1	V_{REF} + 0.1	3.6	0.4	V_{CCO} – 0.4	8	–8
HSTL III	– 0.5	V_{REF} – 0.1	V_{REF} + 0.1	3.6	0.4	V_{CCO} – 0.4	24	–8
HSTL IV	– 0.5	V_{REF} – 0.1	V_{REF} + 0.1	3.6	0.4	V_{CCO} – 0.4	48	–8
SSTL3 I	– 0.5	V_{REF} – 0.2	V_{REF} + 0.2	3.6	V_{REF} – 0.6	V_{REF} + 0.6	8	–8
SSTL3 II	– 0.5	V_{REF} – 0.2	V_{REF} + 0.2	3.6	V_{REF} – 0.8	V_{REF} + 0.8	16	–16
SSTL2 I	– 0.5	V_{REF} – 0.2	V_{REF} + 0.2	3.6	V_{REF} – 0.61	V_{REF} + 0.61	7.6	–7.6
SSTL2 II	– 0.5	V_{REF} – 0.2	V_{REF} + 0.2	3.6	V_{REF} – 0.80	V_{REF} + 0.80	15.2	–15.2

CLB Arithmetic Switching Characteristics

Setup times not listed explicitly can be approximated by decreasing the combinatorial delays by the setup time adjustment listed. Precise values are provided by the timing analyzer.

Description	Symbol	Speed Grade(1)				Units
		Min	-8	-7	-6	
Combinatorial Delays						
F operand inputs to X via XOR	T_{OPX}	0.32	0.68	0.8	0.8	ns, max
F operand input to XB output	T_{OPXB}	0.35	0.65	0.8	0.9	ns, max
F operand input to Y via XOR	T_{OPY}	0.59	1.07	1.4	1.5	ns, max
F operand input to YB output	T_{OPYB}	0.48	0.89	1.1	1.3	ns, max
F operand input to COUT output	T_{OPCYF}	0.37	0.71	0.9	1.0	ns, max
G operand inputs to Y via XOR	T_{OPGY}	0.34	0.72	0.8	0.9	ns, max
G operand input to YB output	T_{OPGYB}	0.47	0.78	1.2	1.3	ns, max
G operand input to COUT output	T_{OPCYG}	0.36	0.60	0.9	1.0	ns, max
BX initialization input to COUT	T_{BXCY}	0.19	0.36	0.51	0.57	ns, max
CIN input to X output via XOR	T_{CINX}	0.27	0.50	0.6	0.7	ns, max
CIN input to XB	T_{CINXB}	0.02	0.04	0.07	0.08	ns, max
CIN input to Y via XOR	T_{CINY}	0.26	0.45	0.7	0.7	ns, max
CIN input to YB	T_{CINYB}	0.16	0.28	0.38	0.43	ns, max
CIN input to COUT output	T_{BYP}	0.05	0.10	0.14	0.15	ns, max
Multiplier Operation						
F1/2 operand inputs to XB output via AND	T_{FANDXB}	0.10	0.30	0.35	0.39	ns, max
F1/2 operand inputs to YB output via AND	T_{FANDYB}	0.28	0.56	0.7	0.8	ns, max
F1/2 operand inputs to COUT output via AND	T_{FANDCY}	0.17	0.38	0.46	0.51	ns, max
G1/2 operand inputs to YB output via AND	T_{GANDYB}	0.20	0.46	0.55	0.7	ns, max
G1/2 operand inputs to COUT output via AND	T_{GANDCY}	0.09	0.28	0.30	0.34	ns, max
Setup and Hold Times before/after Clock CLK						
CIN input to FFX	T_{CCKX}/T_{CKCX}	0.47 / 0	1.0 / 0	1.2 / 0	1.3 / 0	ns, min
CIN input to FFY	T_{CCKY}/T_{CKCY}	0.49 / 0	0.92 / 0	1.2 / 0	1.3 / 0	ns, min

Notes:

1. A Zero “0” Hold Time listing indicates no hold time or a negative hold time. Negative values can not be guaranteed “best-case”, but if a “0” is listed, there is no positive hold time.

Virtex-E Pin-to-Pin Input Parameter Guidelines

All devices are 100% functionally tested. Listed below are representative values for typical pin locations and normal clock loading. Values are expressed in nanoseconds unless otherwise noted

Global Clock Set-Up and Hold for LVTTL Standard, *with* DLL

Description[1]	Symbol	Device	Speed Grade[2, 3]				Units
			Min	-8	-7	-6	
Input Setup and Hold Time Relative to Global Clock Input Signal for LVTTL Standard. For data input with different standards, adjust the setup time delay by the values shown in **IOB Input Switching Characteristics Standard Adjustments**, page 8.							
No Delay	T_{PSDLL}/T_{PHDLL}	XCV50E	1.5 / –0.4	1.5 / –0.4	1.6 / –0.4	1.7 / –0.4	ns
Global Clock and IFF, with DLL		XCV100E	1.5 / –0.4	1.5 / –0.4	1.6 / –0.4	1.7 / –0.4	ns
		XCV200E	1.5 / –0.4	1.5 / –0.4	1.6 / –0.4	1.7 / –0.4	ns
		XCV300E	1.5 / –0.4	1.5 / –0.4	1.6 / –0.4	1.7 / –0.4	ns
		XCV400E	1.5 / –0.4	1.5 / –0.4	1.6 / –0.4	1.7 / –0.4	ns
		XCV600E	1.5 / –0.4	1.5 / –0.4	1.6 / –0.4	1.7 / –0.4	ns
		XCV1000E	1.5 / –0.4	1.5 / –0.4	1.6 / –0.4	1.7 / –0.4	ns
		XCV1600E	1.5 / –0.4	1.5 / –0.4	1.6 / –0.4	1.7 / –0.4	ns
		XCV2000E	1.5 / –0.4	1.5 / –0.4	1.6 / –0.4	1.7 / –0.4	ns
		XCV2600E	1.5 / –0.4	1.5 / –0.4	1.6 / –0.4	1.7 / –0.4	ns
		XCV3200E	1.5 / –0.4	1.5 / –0.4	1.6 / –0.4	1.7 / –0.4	ns

Notes:
1. IFF = Input Flip-Flop or Latch
2. Setup time is measured relative to the Global Clock input signal with the fastest route and the lightest load. Hold time is measured relative to the Global Clock input signal with the slowest route and heaviest load.
3. DLL output jitter is already included in the timing calculation.

Pinout Differences Between Virtex and Virtex-E Families

The same device in the same package for the Virtex-E and Virtex families are pin-compatible with some minor exceptions, listed in Table 1.

XCV200E Device, FG456 Package

The Virtex-E XCV200E has two I/O pins swapped with the Virtex XCV200 to accommodate differential clock pairing.

XCV400E Device, FG676 Package

The Virtex-E XCV400E has two I/O pins swapped with the Virtex XCV400 to accommodate differential clock pairing.

All Devices, PQ240 and HQ240 Packages

The Virtex devices in PQ240 and HQ240 packages do not have V_{CCO} banking, but Virtex-E devices do. To achieve this, eight Virtex I/O pins (P232, P207, P176, P146, P116, P85, P55, and P25) are now VCCO pins in the Virtex-E family. This change also requires one Virtex I/O or VREF pin to be swapped with a standard I/O pin.

Additionally, accommodating differential clock input pairs in Virtex-E caused some IO_V_{REF} differences in the XCV400E and XCV600E devices only. Virtex IO_V_{REF} pins P215 and P87 are Virtex-E IO_V_{REF} pins P216 and P86, respectively. Virtex-E pins P215 and P87 are IO_DLL.

Table 1: **Pinout Differences Summary**

Part	Package	Pins	Virtex	Virtex-E
XCV200	FG456	E11, U11	I/O	No Connect
		B11, AA11	No Connect	IO_LVDS_DLL
XCV400	FG676	D13, Y13	I/O	No Connect
		B13, AF13	No Connect	IO_LVDS_DLL
XCV400/600	PQ240/HQ240	P215, P87	IO_V_{REF}	IO_LVDS_DLL
		P216, P86	I/O	IO_V_{REF}
All	PQ240/HQ240	P232, P207, P176, P146, P116, P85, P55, and P25	I/O	V_{CCO}
		P231	I/O	IO_V_{REF}

Table 14: **BG560 — XCV400E, XCV600E, XCV1000E, XCV1600E, XCV2000E**

Bank	Pin Description	Pin#	See Note
NA	VCCINT	N29	
NA	VCCINT	N33	
NA	VCCINT	U5	
NA	VCCINT	U30	
NA	VCCINT	Y2	
NA	VCCINT	Y31	
NA	VCCINT	AB2	
NA	VCCINT	AB32	
NA	VCCINT	AD2	
NA	VCCINT	AD32	
NA	VCCINT	AG3	
NA	VCCINT	AG31	
NA	VCCINT	AJ13	
NA	VCCINT	AK8	
NA	VCCINT	AK11	
NA	VCCINT	AK17	
NA	VCCINT	AK20	
NA	VCCINT	AL14	
NA	VCCINT	AL22	
NA	VCCINT	AL27	
NA	VCCINT	AN25	
0	VCCO	A22	
0	VCCO	A26	
0	VCCO	A30	
0	VCCO	B19	
0	VCCO	B32	
1	VCCO	A10	
1	VCCO	A16	
1	VCCO	B13	
1	VCCO	C3	
1	VCCO	E5	
2	VCCO	B2	
2	VCCO	D1	
2	VCCO	H1	

Table 14: **BG560 — XCV400E, XCV600E, XCV1000E, XCV1600E, XCV2000E**

Bank	Pin Description	Pin#	See Note
2	VCCO	M1	
2	VCCO	R2	
3	VCCO	V1	
3	VCCO	AA2	
3	VCCO	AD1	
3	VCCO	AK1	
3	VCCO	AL2	
4	VCCO	AN4	
4	VCCO	AN8	
4	VCCO	AN12	
4	VCCO	AM2	
4	VCCO	AM15	
5	VCCO	AL31	
5	VCCO	AM21	
5	VCCO	AN18	
5	VCCO	AN24	
5	VCCO	AN30	
6	VCCO	W32	
6	VCCO	AB33	
6	VCCO	AF33	
6	VCCO	AK33	
6	VCCO	AM32	
7	VCCO	C32	
7	VCCO	D33	
7	VCCO	K33	
7	VCCO	N32	
7	VCCO	T33	
NA	GND	A1	
NA	GND	A7	
NA	GND	A12	
NA	GND	A14	
NA	GND	A18	
NA	GND	A20	
NA	GND	A24	

Table 16: **FG256 Package — XCV50E, XCV100E, XCV200E, XCV300E**

Bank	Pin Description	Pin #
NA	GND	K11
NA	GND	K10
NA	GND	K9
NA	GND	K8
NA	GND	K7
NA	GND	K6
NA	GND	J10
NA	GND	J9
NA	GND	J8
NA	GND	J7
NA	GND	H10
NA	GND	H9
NA	GND	H8
NA	GND	H7
NA	GND	G11
NA	GND	G10
NA	GND	G9
NA	GND	G8
NA	GND	G7
NA	GND	G6
NA	GND	F11
NA	GND	F10
NA	GND	F7
NA	GND	F6
NA	GND	B15
NA	GND	B2
NA	GND	A16
NA	GND	A1

Notes:
1. V_{REF} or I/O option only in the XCV100E, 200E, 300E; otherwise, I/O option only.
2. V_{REF} or I/O option only in the XCV200E, 300E; otherwise, I/O option only.

FG256 Differential Pin Pairs

Virtex-E devices have differential pin pairs that can also provide other functions when not used as a differential pair. A √ in the AO column indicates that the pin pair can be used as an asynchronous output for all devices provided in this package. Pairs with a note number in the AO column are device dependent. They can have asynchronous outputs if the pin pair are in the same CLB row and column in the device. Numbers in this column refer to footnotes that indicate which devices have pin pairs than can be asynchronous outputs. The Other Functions column indicates alternative function(s) not available when the pair is used as a differential pair or differential clock.

Table 17: **FG256 Differential Pin Pair Summary XCV50E, XCV100E, XCV200E, XCV300E**

Pair	Bank	P Pin	N Pin	AO	Other Functions
Global Differential Clock					
0	4	N8	N9	NA	IO_DLL_L52P
1	5	R8	T8	NA	IO_DLL_L52N
2	1	C9	A8	NA	IO_DLL_L8P
3	0	B8	A7	NA	IO_DLL_L8N
IO LVDS Total Pairs: 83, Asynchronous Outputs: 35					
0	0	A3	C5	7	VREF
1	0	E6	D5	√	-
2	0	A4	B4	√	VREF
3	0	B5	D6	2	-
4	0	A5	C6	√	VREF
5	0	C7	B6	√	-
6	0	C8	D7	1	-
7	0	A6	B7	1	VREF
8	1	A8	A7	NA	IO_LVDS_DLL
9	1	A9	D9	2	-
10	1	B9	E10	1	VREF
11	1	D10	A10	1	-
12	1	A11	C10	√	-
13	1	E11	B11	√	VREF
14	1	D11	A12	2	-
15	1	C11	A13	√	VREF
16	1	D12	B12	√	-
17	1	C12	A14	7	VREF
18	1	B13	C13	√	CS

Table 19: **FG456 Differential Pin Pair Summary XCV200E, XCV300E**

Pair	Bank	P Pin	N Pin	AO	Other Functions
88	5	V7	AB3	√	-
89	6	Y2	W3	√	-
90	6	V3	V4	√	-
91	6	U4	Y1	√	VREF
92	6	W1	V2	√	-
93	6	U2	T3	√	VREF
94	6	V1	T5	2	-
95	6	U1	R5	1	-
96	6	T1	R4	2	VREF
97	6	P3	R2	√	-
98	6	R1	P5	√	-
99	6	N5	P2	√	-
100	6	N4	P1	2	-
101	6	N2	N3	1	VREF
102	6	M4	N1	2	-
103	6	M6	M3	√	-
104	7	L4	L3	√	-
105	7	L1	L5	√	-
106	7	K2	L6	2	-
107	7	K3	K4	2	VREF
108	7	K5	K1	√	-
109	7	J2	J3	√	-
110	7	H1	J5	√	-
111	7	H3	H2	√	-
112	7	H4	G1	2	VREF
113	7	F2	F1	2	-
114	7	G3	H5	√	-
115	7	E2	E1	√	VREF
116	7	G5	F3	√	-
117	7	D2	E3	√	VREF
118	7	C1	F5	√	-

Notes:
1. AO in the XCV200E.
2. AO in the XCV300E.

FG676 Fine-Pitch Ball Grid Array Package

XCV400E and XCV600E devices in the FG676 fine-pitch Ball Grid Array package have footprint compatibility. Pins labeled I0_VREF can be used as either in all parts unless device-dependent as indicated in the footnotes. If the pin is not used as V_{REF}, it can be used as general I/O. Immediately following Table 20, see Table 21 for Differential Pair information.

Table 20: **FG676 — XCV400E, XCV600E**

Bank	Pin Description	Pin #
0	GCK3	E13
0	IO	A6
0	IO	A9[1]
0	IO	A10[1]
0	IO	B3
0	IO	B4[1]
0	IO	B12[1]
0	IO	C6
0	IO	C8
0	IO	D5
0	IO	D13[1]
0	IO	G13
0	IO_L0N_Y	C4
0	IO_L0P_Y	F7
0	IO_L1N_YY	G8
0	IO_L1P_YY	C5
0	IO_VREF_L2N_YY	D6
0	IO_L2P_YY	E7
0	IO_L3N	A4
0	IO_L3P	F8
0	IO_L4N	B5
0	IO_L4P	D7
0	IO_VREF_L5N_YY	E8
0	IO_L5P_YY	G9
0	IO_L6N_YY	A5
0	IO_L6P_YY	F9
0	IO_L7N_Y	D8
0	IO_L7P_Y	C7
0	IO_VREF_L8N_Y	B7[2]
0	IO_L8P_Y	E9

Table 20: **FG676 — XCV400E, XCV600E**

Bank	Pin Description	Pin #
5	IO_L129N_Y	AB9
5	IO_L130P_YY	AA9
5	IO_L130N_YY	AF6
5	IO_L131P_YY	AC8
5	IO_VREF_L131N_YY	AC7
5	IO_L132P_YY	AD6
5	IO_L132N_YY	Y9
5	IO_L133P_YY	AE5
5	IO_L133N_YY	AA8
5	IO_L134P_YY	AC6
5	IO_VREF_L134N_YY	AB8
5	IO_L135P_YY	AD5
5	IO_L135N_YY	AA7
5	IO_L136P_Y	AF4
5	IO_L136N_Y	AC5
6	IO	P3
6	IO	AA3
6	IO	AC1[1]
6	IO	P1[1]
6	IO	R2[1]
6	IO	T1[1]
6	IO	V1[1]
6	IO	W3
6	IO	Y2
6	IO	Y6
6	IO_L137N_YY	AA5
6	IO_L137P_YY	AC3
6	IO_L138N_YY	AC2
6	IO_L138P_YY	AB4
6	IO_L139N_Y	W6
6	IO_L139P_Y	AA4
6	IO_VREF_L140N_Y	AB3
6	IO_L140P_Y	Y5
6	IO_L141N_Y	AB2
6	IO_L141P_Y	V7
6	IO_L142N_YY	AB1

Table 20: **FG676 — XCV400E, XCV600E**

Bank	Pin Description	Pin #
6	IO_L142P_YY	Y4
6	IO_VREF_L143N_YY	V5
6	IO_L143P_YY	W5
6	IO_L144N_YY	AA1
6	IO_L144P_YY	V6
6	IO_L145N_Y	W4
6	IO_L145P_Y	Y3
6	IO_VREF_L146N_Y	Y1[2]
6	IO_L146P_Y	U7
6	IO_L147N_YY	W1
6	IO_L147P_YY	V4
6	IO_L148N_YY	W2
6	IO_VREF_L148P_YY	U6
6	IO_L149N_YY	V3
6	IO_L149P_YY	T5
6	IO_L150N_YY	U5
6	IO_L150P_YY	U4
6	IO_L151N_Y	T7
6	IO_L151P_Y	U3
6	IO_L152N_Y	U2
6	IO_L152P_Y	T6
6	IO_L153N_Y	U1
6	IO_L153P_Y	T4
6	IO_L154N_Y	R7
6	IO_L154P_Y	T3
6	IO_VREF_L155N_YY	R4
6	IO_L155P_YY	R6
6	IO_L156N_YY	R3
6	IO_L156P_YY	R5
6	IO_L157N_Y	P8
6	IO_L157P_Y	P7
6	IO_VREF_L158N_Y	R1
6	IO_L158P_Y	P6
6	IO_L159N_YY	P5
6	IO_L159P_YY	P4
7	IO	D1[1]

Table 20: **FG676 — XCV400E, XCV600E**

Bank	Pin Description	Pin #
NA	GND	P14
NA	GND	P13
NA	GND	P12
NA	GND	P11
NA	GND	P10
NA	GND	N2
NA	GND	N17
NA	GND	N16
NA	GND	N15
NA	GND	N14
NA	GND	N13
NA	GND	N12
NA	GND	N11
NA	GND	N10
NA	GND	M17
NA	GND	M16
NA	GND	M15
NA	GND	M14
NA	GND	M13
NA	GND	M12
NA	GND	M11
NA	GND	M10
NA	GND	L17
NA	GND	L16
NA	GND	L15
NA	GND	L14
NA	GND	L13
NA	GND	L12
NA	GND	L11
NA	GND	L10
NA	GND	K17
NA	GND	K16
NA	GND	K15
NA	GND	K14
NA	GND	K13
NA	GND	K12
NA	GND	K11

Table 20: **FG676 — XCV400E, XCV600E**

Bank	Pin Description	Pin #
NA	GND	K10
NA	GND	J25
NA	GND	J2
NA	GND	E5
NA	GND	E22
NA	GND	D4
NA	GND	D23
NA	GND	C3
NA	GND	C24
NA	GND	B9
NA	GND	B25
NA	GND	B2
NA	GND	B18
NA	GND	B14
NA	GND	AF26
NA	GND	AF1
NA	GND	AE9
NA	GND	AE25
NA	GND	AE2
NA	GND	AE18
NA	GND	AE13
NA	GND	AD3
NA	GND	AD24
NA	GND	AC4
NA	GND	AC23
NA	GND	AB5
NA	GND	AB22
NA	GND	A26
NA	GND	A1

Notes:
1. NC in the XCV400E.
2. V_{REF} or I/O option only in the XCV600E; otherwise, I/O option only.

Table 22: **FG680 - XCV600E, XCV1000E, XCV1600E, XCV2000E**

Bank	Pin Description	Pin #
2	IO_L63N	G4
2	IO_L64P	G3
2	IO_L64N	E2
2	IO_VREF_L65P_Y	H4
2	IO_L65N_Y	E1
2	IO_L66P_YY	H3
2	IO_L66N_YY	F2
2	IO_L67P	J4
2	IO_L67N	F1
2	IO_L68P_Y	J3
2	IO_L68N_Y	G2
2	IO_VREF_L69P_YY	G1
2	IO_L69N_YY	K4
2	IO_L70P_YY	H2
2	IO_L70N_YY	K3
2	IO_VREF_L71P	H1[3]
2	IO_L71N	L4
2	IO_L72P	J2
2	IO_L72N	L3
2	IO_VREF_L73P_YY	J1
2	IO_L73N_YY	M3
2	IO_L74P_YY	K2
2	IO_L74N_YY	N4
2	IO_L75P	K1
2	IO_L75N	N3
2	IO_VREF_L76P_YY	L2
2	IO_D1_L76N_YY	P4
2	IO_D2_L77P_YY	P3
2	IO_L77N_YY	L1
2	IO_L78P_Y	R4
2	IO_L78N_Y	M2
2	IO_L79P	R3
2	IO_L79N	M1
2	IO_L80P	T4
2	IO_L80N	N2
2	IO_VREF_L81P_Y	N1[1]

Table 22: **FG680 - XCV600E, XCV1000E, XCV1600E, XCV2000E**

Bank	Pin Description	Pin #
2	IO_L81N_Y	T3
2	IO_L82P_YY	P2
2	IO_L82N_YY	U5
2	IO_L83P	P1
2	IO_L83N	U4
2	IO_L84P_Y	R2
2	IO_L84N_Y	U3
2	IO_VREF_L85P_YY	V5
2	IO_D3_L85N_YY	R1
2	IO_L86P_YY	V4
2	IO_L86N_YY	T2
2	IO_L87P	V3
2	IO_L87N	T1
2	IO_L88P	W4
2	IO_L88N	U2
2	IO_VREF_L89P_YY	W3
2	IO_L89N_YY	U1
2	IO_L90P_YY	AA3
2	IO_L90N_YY	V2
2	IO_VREF_L91P	AA4[2]
2	IO_L91N	V1
2	IO_L92P_YY	AB2
2	IO_L92N_YY	W2
3	IO	AP3
3	IO	AT3
3	IO	AB3
3	IO_L93P	AB4
3	IO_VREF_L93N	W1[2]
3	IO_L94P_YY	AB5
3	IO_L94N_YY	Y2
3	IO_L95P_YY	AC2
3	IO_VREF_L95N_YY	Y1
3	IO_L96P	AC3
3	IO_L96N	AA1
3	IO_L97P	AC4

Table 24: **FG860 — XCV1000E, XCV1600E, XCV2000E**

Bank	Pin Description	Pin #
6	IO	AJ40
6	IO	AL41
6	IO	AN38
6	IO	AN42
6	IO	AP41
6	IO	AR39
6	IO_L211N_YY	AV41
6	IO_L211P_YY	AV42
6	IO_L212N_Y	AW40
6	IO_L212P_Y	AU41
6	IO_L213N_Y	AV39
6	IO_L213P_Y	AU42
6	IO_VREF_L214N_Y	AT41
6	IO_L214P_Y	AU38
6	IO_L215N	AT42
6	IO_L215P	AV40
6	IO_L216N_Y	AR41
6	IO_L216P_Y	AU39
6	IO_VREF_L217N_Y	AR42
6	IO_L217P_Y	AU40
6	IO_L218N_YY	AT38
6	IO_L218P_YY	AP42
6	IO_L219N_Y	AN41
6	IO_L219P_Y	AT39
6	IO_L220N_Y	AT40
6	IO_L220P_Y	AM40
6	IO_VREF_L221N_YY	AR38
6	IO_L221P_YY	AM41
6	IO_L222N_YY	AM42
6	IO_L222P_YY	AR40
6	IO_VREF_L223N_Y	AL40[2]
6	IO_L223P_Y	AP38
6	IO_L224N_Y	AP39
6	IO_L224P_Y	AL42
6	IO_VREF_L225N_YY	AP40
6	IO_L225P_YY	AK40
6	IO_L226N_YY	AK41

Table 24: **FG860 — XCV1000E, XCV1600E, XCV2000E**

Bank	Pin Description	Pin #
6	IO_L226P_YY	AN39
6	IO_L227N_Y	AK42
6	IO_L227P_Y	AN40
6	IO_VREF_L228N_YY	AM38
6	IO_L228P_YY	AJ41
6	IO_L229N_YY	AJ42
6	IO_L229P_YY	AM39
6	IO_L230N_Y	AH40
6	IO_L230P_Y	AH41
6	IO_L231N_Y	AL38
6	IO_L231P_Y	AH42
6	IO_L232N_Y	AL39
6	IO_L232P_Y	AG41
6	IO_L233N	AK39
6	IO_L233P	AG40
6	IO_L234N_Y	AJ38
6	IO_L234P_Y	AG42
6	IO_VREF_L235N_Y	AF42
6	IO_L235P_Y	AJ39
6	IO_L236N_YY	AF41
6	IO_L236P_YY	AH38
6	IO_L237N_Y	AE42
6	IO_L237P_Y	AH39
6	IO_L238N_Y	AG38
6	IO_L238P_Y	AE41
6	IO_VREF_L239N_YY	AG39
6	IO_L239P_YY	AD42
6	IO_L240N_YY	AD40
6	IO_L240P_YY	AF39
6	IO_L241N_Y	AD41
6	IO_L241P_Y	AE38
6	IO_L242N_Y	AE39
6	IO_L242P_Y	AC40
6	IO_VREF_L243N_YY	AD38
6	IO_L243P_YY	AC41
6	IO_L244N_YY	AB42
6	IO_L244P_YY	AC38

Table 24: **FG860 — XCV1000E, XCV1600E, XCV2000E**

Bank	Pin Description	Pin #
NA	GND	C42
NA	GND	C41
NA	GND	C40
NA	GND	C3
NA	GND	C2
NA	GND	C1
NA	GND	BB41
NA	GND	BB40
NA	GND	BB4
NA	GND	BB39
NA	GND	BB3
NA	GND	BB2
NA	GND	BA42
NA	GND	BA41
NA	GND	BA40
NA	GND	BA3
NA	GND	BA2
NA	GND	BA1
NA	GND	B42
NA	GND	B41
NA	GND	B40
NA	GND	B3
NA	GND	B2
NA	GND	B1
NA	GND	AY42
NA	GND	AY41
NA	GND	AY40
NA	GND	AY3
NA	GND	AY2
NA	GND	AY1
NA	GND	AW42
NA	GND	AW4
NA	GND	AW39
NA	GND	AW1
NA	GND	AV5
NA	GND	AV38
NA	GND	AV30

Table 24: **FG860 — XCV1000E, XCV1600E, XCV2000E**

Bank	Pin Description	Pin #
NA	GND	AV22
NA	GND	AV21
NA	GND	AV13
NA	GND	AU6
NA	GND	AU37
NA	GND	AU30
NA	GND	AU22
NA	GND	AU21
NA	GND	AU13
NA	GND	AK6
NA	GND	AK5
NA	GND	AK38
NA	GND	AK37
NA	GND	AB6
NA	GND	AB5
NA	GND	AB38
NA	GND	AB37
NA	GND	AA6
NA	GND	AA5
NA	GND	AA38
NA	GND	AA37
NA	GND	A41
NA	GND	A40
NA	GND	A4
NA	GND	A39
NA	GND	A3
NA	GND	A2

Notes:
1. V_{REF} or I/O option only in the XCV1600E, 2000E; otherwise, I/O option only.
2. V_{REF} or I/O option only in the XCV2000E; otherwise, I/O option only.

Table 26: **FG900 — XCV600E, XCV1000E, XCV1600E**

Bank	Pin Description	Pin #
0	IO_L6N_Y	A5
0	IO_L6P_Y	F8
0	IO_L7N_Y	D7
0	IO_L7P_Y	N11
0	IO_L8N_YY	G9
0	IO_L8P_YY	E8
0	IO_VREF_L9N_YY	A6
0	IO_L9P_YY	J11
0	IO_L10N_Y	C7
0	IO_L10P_Y	B7
0	IO_L11N_Y	C8
0	IO_L11P_Y	H10
0	IO_L12N_YY	G10
0	IO_L12P_YY	F10
0	IO_VREF_L13N_YY	A8
0	IO_L13P_YY	H11
0	IO_L14N	D9[4]
0	IO_L14P	C9[3]
0	IO_L15N_YY	B9
0	IO_L15P_YY	J12
0	IO_L16N	E10[4]
0	IO_VREF_L16P	A9
0	IO_L17N	G11
0	IO_L17P	B10
0	IO_L18N_YY	H12[4]
0	IO_L18P_YY	C10[4]
0	IO_L19N_Y	H13
0	IO_L19P_Y	F11
0	IO_L20N_Y	E11
0	IO_L20P_Y	D11
0	IO_L21N_Y	B11[4]
0	IO_L21P_Y	G12[4]
0	IO_L22N_YY	F12
0	IO_L22P_YY	C11
0	IO_VREF_L23N_YY	A10[1]
0	IO_L23P_YY	D12
0	IO_L24N_Y	E12

Table 26: **FG900 — XCV600E, XCV1000E, XCV1600E**

Bank	Pin Description	Pin #
0	IO_L24P_Y	A11
0	IO_L25N_Y	G13
0	IO_L25P_Y	B12
0	IO_L26N_YY	A12
0	IO_L26P_YY	K13
0	IO_VREF_L27N_YY	F13
0	IO_L27P_YY	B13
0	IO_L28N_Y	G14
0	IO_L28P_Y	E13
0	IO_L29N_Y	D14
0	IO_L29P_Y	B14
0	IO_L30N_YY	A14
0	IO_L30P_YY	J14
0	IO_VREF_L31N_YY	K14
0	IO_L31P_YY	J15
0	IO_L32N	B15[4]
0	IO_L32P	H15[3]
0	IO_VREF_L33N_YY	F15[2,3]
0	IO_L33P_YY	D15[4]
0	IO_LVDS_DLL_L34N	A15
1	GCK2	E15
1	IO	A25[4]
1	IO	B17[4]
1	IO	B18[4]
1	IO	C23[4]
1	IO	D16[4]
1	IO	D17[5]
1	IO	D23[4]
1	IO	E19[4]
1	IO	E24[5]
1	IO	F22[4]
1	IO	G17[5]
1	IO	G20[4]
1	IO	J16[4]
1	IO	J17[4]
1	IO	J19[5]

Table 26: **FG900 — XCV600E, XCV1000E, XCV1600E**

Bank	Pin Description	Pin #
7	IO	E3
7	IO	F1[4]
7	IO	G1[5]
7	IO	G4[5]
7	IO	H3[5]
7	IO	J1[4]
7	IO	J3[4]
7	IO	J4[4]
7	IO	J6[4]
7	IO	L10[4]
7	IO	N2[4]
7	IO	N8[4]
7	IO	N10[4]
7	IO	P3[5]
7	IO	P9[4]
7	IO	R1[5]
7	IO	T3[4]
7	IO_L247P	R10
7	IO_L248N_YY	R5[3]
7	IO_L248P_YY	R6[4]
7	IO_L249N_YY	R8
7	IO_VREF_L249P_YY	R4[2]
7	IO_L250N_YY	R7
7	IO_L250P_YY	R3
7	IO_L251N_YY	P10
7	IO_VREF_L251P_YY	P6
7	IO_L252N_YY	P5
7	IO_L252P_YY	P2
7	IO_L253N	P7
7	IO_L253P	P4
7	IO_L254N_YY	N4
7	IO_L254P_YY	R2
7	IO_L255N_YY	N7
7	IO_VREF_L255P_YY	P1
7	IO_L256N	M6

Table 26: **FG900 — XCV600E, XCV1000E, XCV1600E**

Bank	Pin Description	Pin #
7	IO_L256P	N6
7	IO_L257N_YY	N5
7	IO_L257P_YY	N1
7	IO_L258N_YY	M4
7	IO_L258P_YY	M5
7	IO_L259N	M2
7	IO_VREF_L259P	M1[1]
7	IO_L260N_YY	L4
7	IO_L260P_YY	L2
7	IO_L261N_Y	M7[4]
7	IO_L261P_Y	L5[4]
7	IO_L262N_YY	L1
7	IO_L262P_YY	M8
7	IO_L263N	K2
7	IO_L263P	M9
7	IO_L264N	L3[4]
7	IO_L264P	M10[4]
7	IO_L265N_YY	K5
7	IO_L265P_YY	K1
7	IO_L266N_YY	L6
7	IO_VREF_L266P_YY	K3
7	IO_L267N_YY	L7
7	IO_L267P_YY	K4
7	IO_L268N_YY	L8
7	IO_L268P_YY	J5
7	IO_L269N_YY	K6
7	IO_VREF_L269P_YY	H4
7	IO_L270N_YY	H1
7	IO_L270P_YY	K7
7	IO_L271N	J7
7	IO_L271P	J2
7	IO_L272N_YY	H5
7	IO_L272P_YY	G2
7	IO_L273N_YY	L9
7	IO_VREF_L273P_YY	G5
7	IO_L274N	F3
7	IO_L274P	K8

Table 28: **FG1156 — XCV1000E, XCV1600E, XCV2000E, XCV2600E, XCV3200E**

Bank	Pin Description	Pin #
NA	GND	AP2
NA	GND	AN3
NA	GND	AM20
NA	GND	AK30
NA	GND	AG8
NA	GND	AC29
NA	GND	Y3
NA	GND	Y32
NA	GND	W21
NA	GND	V21
NA	GND	T8
NA	GND	T27
NA	GND	R21
NA	GND	P21
NA	GND	H19
NA	GND	F29
NA	GND	C11
NA	GND	B3
NA	GND	A32
NA	GND	AP3
NA	GND	AN32
NA	GND	AM24
NA	GND	AJ6
NA	GND	AG16
NA	GND	AA14
NA	GND	Y14
NA	GND	W8
NA	GND	W27
NA	GND	U14
NA	GND	T14
NA	GND	R3
NA	GND	R32
NA	GND	M6
NA	GND	H27

Table 28: **FG1156 — XCV1000E, XCV1600E, XCV2000E, XCV2600E, XCV3200E**

Bank	Pin Description	Pin #
NA	GND	E5
NA	GND	C15
NA	GND	B32
NA	GND	A33
NA	GND	AP7
NA	GND	AN33
NA	GND	AM32
NA	GND	AJ12
NA	GND	AG19
NA	GND	AA15
NA	GND	Y15
NA	GND	W14
NA	GND	V14
NA	GND	U15
NA	GND	T15
NA	GND	R14
NA	GND	P14
NA	GND	M29
NA	GND	G1
NA	GND	E18
NA	GND	C20
NA	GND	B33
NA	GND	A34
NA	GND	AP28
NA	GND	AN34
NA	GND	AM33
NA	GND	AJ23
NA	GND	AG27
NA	GND	AA16
NA	GND	Y16
NA	GND	W15
NA	GND	V15
NA	GND	U16
NA	GND	T16

Table 29: **FG1156 Differential Pin Pair Summary: XCV1000E, XCV1600E, XCV2000E, XCV2600E, XCV3200E**

Pair	Bank	P Pin	N Pin	AO	Other Functions
231	5	AH14	AP12	3200 2600 2000 1600 1000	-
232	5	AJ14	AL14	3200 2600 1000	-
233	5	AF13	AN12	3200 2000 1000	-
234	5	AF14	AP11	3200 2000 1000	-
235	5	AN11	AH13	3200 1600 1000	-
236	5	AM12	AL12	3200 2600 2000 1600 1000	-
237	5	AJ13	AP10	3200 2600 2000 1600 1000	VREF
238	5	AK12	AM10	2600 1600 1000	-
239	5	AP9	AK11	2600 1600 1000	-
240	5	AL11	AL10	3200 2600 2000 1600 1000	VREF
241	5	AE13	AM9	3200 2600 2000 1600 1000	-
242	5	AF12	AP8	3200 2600	-
243	5	AL9	AH11	3200 2000 1000	VREF
244	5	AF11	AN8	3200 2000 1000	-
245	5	AM8	AG11	3200 1600	-
246	5	AL8	AK9	3200 2600 2000 1600 1000	VREF
247	5	AH10	AN7	3200 2600 2000 1600 1000	-
248	5	AE12	AJ9	3200 2600	-
249	5	AM7	AL7	3200 1000	-
250	5	AG10	AN6	3200 1000	-

Table 29: **FG1156 Differential Pin Pair Summary: XCV1000E, XCV1600E, XCV2000E, XCV2600E, XCV3200E**

Pair	Bank	P Pin	N Pin	AO	Other Functions
251	5	AK8	AH9	2000 1600	-
252	5	AP5	AJ8	3200 2600 2000 1600 1000	VREF
253	5	AE11	AN5	3200 2600 2000 1600 1000	-
254	5	AF10	AM6	3200 2600 1000	-
255	5	AL6	AG9	3200 2000 1000	VREF
256	5	AH8	AP4	3200 2000 1000	-
257	5	AN4	AJ7	3200 1600 1000	-
258	5	AM5	AK6	3200 2600 2000 1600 1000	-
259	6	AF8	AH6	3200 2600 2000 1600 1000	-
260	6	AK3	AE9	3200 2600 2000	-
261	6	AL2	AD10	2600 2000 1000	-
262	6	AH4	AL1	3200 2600 1600 1000	VREF
263	6	AK1	AG6	2600 1600	-
264	6	AK2	AF7	3200 2600 1600 1000	-
265	6	AG5	AJ3	2600 2000 1000	VREF
266	6	AJ2	AD9	3200 2600 2000 1600	-
267	6	AH2	AC10	3200 2600 2000 1600 1000	-
268	6	AF5	AH3	3200 2600 1600 1000	-
269	6	AG3	AE8	3200 2600 2000	-